



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSO110N03MS G	Issued	14. April 2021
MA#	MA005400460		
Package	PG-DSO-8-39	Weight*	83.34 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.614	0.74	0.74	7364	7364
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		123	
	non noble metal	zinc	7440-66-6	0.041	0.05		492	
	non noble metal	iron	7439-89-6	0.820	0.98		9834	
	non noble metal	copper	7440-50-8	33.276	39.93	40.97	399281	409730
wire	non noble metal	copper	7440-50-8	0.192	0.23	0.23	2299	2299
encapsulation	organic material	carbon black	1333-86-4	0.236	0.28		2831	
	plastics	epoxy resin	-	7.314	8.78		87765	
	inorganic material	silicondioxide	60676-86-0	39.638	47.55	56.61	475628	566224
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9765	9765
plating	noble metal	silver	7440-22-4	0.073	0.09	0.09	871	871
glue	plastics	epoxy resin	-	0.047	0.06		562	
	noble metal	silver	7440-22-4	0.265	0.32	0.38	3185	3747
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com